

# Bill of Materials

	SCM	SCC	Remarks
Die Attach	Ablestik 3230	Ablestik 3230	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

# Reliability Qualification Result for LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION RESULT			
Test	Conditions	Sample Size	Result
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 45	PASS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 45	PASS
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 45	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 45	PASS
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	PASS ±1250V

\*Preconditioned per JEDEC/IPC J-STD-020